

AMENDMENTS TO THE CLAIMS

• Please amend the Claims as follows:

1. (PREVIOUSLY AMENDED) A temporarily protected wafer, comprising:
a sensitive area disposed on a surface of the wafer; and
a vapor-deposited, water-insoluble temporary protective coating directly contacting and
covering the sensitive area;
wherein the protective coating is insoluble in organic solvents;
wherein the coating remains in place during singulation of the wafer into individual device
dies; and further
wherein a sufficient amount of the coating is removed to activate the sensitive area prior to
completing packaging of the die.
2. (original) The temporarily protected wafer of claim 1, wherein the sensitive area comprises a
released MEMS device.
3. (original) The temporarily protected wafer of claim 1, wherein the sensitive area comprises a
pressure-sensitive microsensor.
4. (original) The temporarily protected wafer of claim 1, wherein the sensitive area comprises a
chemically sensitive microsensor.
5. (original) The temporarily protected wafer of claim 1, wherein the sensitive area comprises a
temperature-sensitive microsensor.
6. (original) The temporarily protected wafer of claim 1, wherein the sensitive area comprises a
released IMEMS device.
7. (original) The temporarily protected wafer of claim 1, wherein the temporary protective
coating comprises a vacuum vapor-deposited coating.
8. (original) The temporarily protected wafer of claim 7, wherein the vacuum vapor-deposited
coating comprises a parylene polymer.
9. (original) The temporarily protected wafer of claim 8, wherein the parylene coating is selected
from the group of parylene polymers consisting of poly-para-xylylene, poly-para-xylylene
modified by the substitution of a chlorine atom for one aromatic hydrogen, and poly-
para-xylylene modified by the substitution of a chlorine atom for two aromatic hydrogens.

10. (PREVIOUSLY AMENDED) The temporarily protected wafer of claim 8, wherein the parylene coating comprises a copolymer compound formed by blending a reactive parylene monomer with a reactive material.
11. (original) The temporarily protected wafer of claim 10, wherein the reactive material comprises a monomer containing an element selected from the group consisting of silicon, carbon, and fluorine, and combinations thereof.
12. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises silicon dioxide, silicate glass, or silicon nitride.
13. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a metal.
14. (original) The temporarily protected wafer of claim 13, wherein the metal comprises aluminum or tungsten.
15. (CANCELLED)
16. (CANCELLED)
17. (PREVIOUSLY AMENDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises one or more materials selected from the group consisting of a carbon film, an amorphous carbon film, and a diamond-like carbon film.
18. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises a self-assembled monolayered material.
19. (PREVIOUSLY AMENDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating comprises perfluoropolyether.
20. (original) The temporarily protected wafer of claim 1, further comprising exposed bond pads.
21. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited using a Chemical Vapor Deposition (CVD) process.
22. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited using a Plasma Enhanced Chemical Vapor Deposition (PACVD) process.
23. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited at essentially ambient temperature.
24. (original) The temporarily protected wafer of claim 1, wherein the temporary protective coating is deposited by polymerizing a monomeric gas on at least the sensitive area.
25. (PREVIOUSLY AMENDED) A temporarily protected die, comprising:
a sensitive area disposed on a surface of the die; and

a vapor-deposited, water-insoluble temporary protective coating directly contacting and covering the sensitive area;

wherein the protective coating is insoluble in organic solvents; and

wherein a sufficient amount of the coating is removed to activate the sensitive area prior to completing packaging of the die.

26. (original) The temporarily protected die of claim 25, wherein the sensitive area comprises a released MEMS device.

27. (original) The temporarily protected die of claim 26, wherein the temporary protective coating comprises a parylene polymer.

28. (CURRENTLY AMENDED) A temporarily protected wafer, comprising:

a sensitive area disposed on a surface of the wafer comprising a released MEMS device having a released MEMS element;

a performance-enhancing coating disposed directly on the released MEMS element; and

a vapor-deposited, water-insoluble temporary protective coating disposed directly on top of the performance-enhancing coating;

wherein the protective coating is insoluble in organic solvents; and

wherein the coating remains in place during singulation of the wafer into individual device dies, and further wherein a sufficient amount of the coating is removed to re-release the MEMS element prior to completing packaging of the die, without removing the performance-enhancing coating.

29. (PREVIOUSLY AMENDED) The temporarily protected wafer of claim 28, wherein the performance-enhancing coating comprises one or more materials selected from the group consisting of an anti-stiction film, an adhesion-inhibiting film, a lubricant, and a nitrided-surface.

30. (PREVIOUSLY AMENDED) The temporarily protected wafer of claim 28, wherein the performance-enhancing coating comprises one or more materials selected from the group consisting of perfluoropolyether, hexamethyldisilazane, and perfluorodecanoic carboxylic acid.

31. (CANCELLED)

32. (CANCELLED)

33. (CANCELLED)

34. (CANCELLED)

35. (PREVIOUSLY ADDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating is insoluble in organic solvents heated to less than or equal to 150 C.

36. (PREVIOUSLY ADDED) The temporarily protected wafer of claim 1, wherein the temporary protective coating is excluded from covering any wafer streets.
37. (PREVIOUSLY ADDED) The protected die of claim 25, wherein the die is mechanically attached and electrically interconnected to a package.
38. (PREVIOUSLY ADDED) The die of claim 37, wherein the sensitive area comprises a released MEMS element.
39. (PREVIOUSLY ADDED) The die of claim 37, wherein the die is wirebonded to the package.
40. (PREVIOUSLY ADDED) The die of claim 37, wherein the die is flip-chip bonded to the package.
41. (PREVIOUSLY ADDED) The die of claim 38, wherein the temporary protective coating is sufficiently thick so as to immobilize the released MEMS element.
42. (PREVIOUSLY ADDED) The die of claim 38, wherein the temporary protective coating is sufficiently thin so as to not immobilize the released MEMS element.
43. (PREVIOUSLY ADDED) A protected die, comprising:
a sensitive area disposed on a surface of the die, the area comprising a released MEMS device having a released MEMS element;
a performance-enhancing coating disposed directly on the released MEMS element; and
a vapor-deposited, water-insoluble temporary protective coating disposed directly on top of the performance-enhancing coating;
wherein the protective coating is insoluble in organic solvents; and
wherein the die is attached and electrically interconnected to a package.
44. (PREVIOUSLY ADDED) The die of claim 43, wherein the temporary protective coating is sufficiently thin so as to not immobilize the released MEMS element.